Low Power Peak EMI Reducing Solution

Features

- Generates an EMI optimized clock signal at the output.
- Integrated loop filter components.
- Operates with a 3.3V / 2.5V Supply.
- Operating current less than 4mA.
- Low power CMOS design.
- Input frequency range: 6MHz to 12MHz for 2.5V.

: 6MHz to 13MHz for 3.3V.

- Generates a 1X low EMI spread spectrum clock of the input frequency.
- Frequency deviation: ±0.65% @ 8MHz
- Available in 6-pin TSOT-23, 8-pin SOIC and 8-pin TSSOP packages.

Product Description

The ASM3P2760A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. The ASM3P2760A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of all clock dependent signals. The ASM3P2760A allows significant system cost savings by reducing the number of circuit board layers ferrite beads, shielding that are traditionally required to pass EMI regulations.

The ASM3P2760A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all digital method.

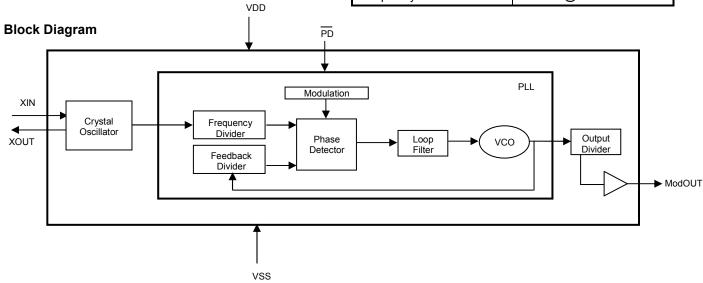
The ASM3P2760A modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal's bandwidth is called 'spread spectrum clock generation'.

Applications

The ASM3P2760A is targeted towards all portable devices with very low power requirements like MP3 players and digital still cameras.

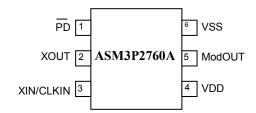
Key Specifications

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Description	Specification
Supply voltages	V _{DD} = 3.3V / 2.5V
Cycle-to-Cycle Jitter	200 pS (Max)
Output Duty Cycle	45/55% (worst case)
Modulation Rate Equation	F _{IN} /256
Frequency Deviation	±0.65% @ 8MHz





Pin Configuration (6-pin TSOT-23)

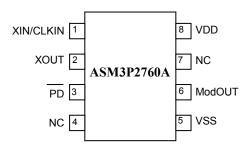


Pin#	Pin Name	Туре	Description
1	PD	I	Power-down control pin. Pull low to enable power-down mode. Connect to VDD if not used.
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.
3	XIN/CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
4	VDD	Р	Power supply for the entire chip
5	ModOUT	0	Spread spectrum clock output.
6	VSS	Р	Ground connection.



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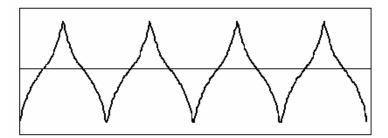
Pin Configuration (8-pin SOIC and TSSOP Packages)



Pin Description

Pin#	Pin Name	Туре	Description
1	XIN/CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.
3	PD	1	Power-down control pin. Pull low to enable power-down mode. Connect to VDD if not used.
4	NC	-	No connect.
5	VSS	Р	Ground connection.
6	ModOUT	0	Spread spectrum clock output.
7	NC	_	No connect.
8	VDD	Р	Power supply for the entire chip

Modulation Profile



Specification

Description		Specification
Frequency Range	For 2.5V Supply	6MHz < CLKIN < 12MHz
Frequency Kange	For 3.3V Supply	6MHz < CLKIN < 13MHz
Modulation Equation		F _{IN} /256
	Frequency Deviation	±0.65% @ 8MHz



rev 1.7 **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit
V_{DD} , V_{IN}	Voltage on any pin with respect to Ground	0.5 to +7.0	V
T _{STG}	Storage temperature	-65 to +125	°C
T _A	Operating temperature	0 to 70	°C
Ts	Max. Soldering Temperature (10 sec)	260	°C
TJ	Junction Temperature	150	°C
T_DV	Static Discharge Voltage (As per MIL-STD-883, Method 3015)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

DC Electrical Characteristics for 2.5V Supply

(Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated)

Symbol	Parameter	Min	Тур	Max	Unit
V_{IL}	Input low voltage	GND-0.3	_	0.8	V
V_{IH}	Input high voltage	2.0	_	VDD+0.3	V
I _{IL}	Input low current	_	_	-35	μA
I _{IH}	Input high current	_	_	35	μA
I _{XOL}	XOUT output low current (@0.5V, V _{DD} =2.5V)	_	3	_	mA
I _{XOH}	XOUT output high current (@1.8V, V _{DD} =2.5V)	_	3	_	mA
V _{OL}	Output low voltage (V _{DD} = 2.5 V, I _{OL} = 8 mA)	_	_	0.6	V
V _{OH}	Output high voltage (V _{DD} = 2.5 V, I _{OH} = 8 mA)	1.8	_	_	V
I_{DD}	Static supply current*	_	_	10	μA
Icc	Dynamic supply current (2.5V, 8MHz and no load)	_	2.5	_	mA
V_{DD}	Operating voltage	2.375	2.5	2.625	V
t _{ON}	Power-up time (first locked cycle after power-up)**	_	_	5	mS
Z _{out}	Output impedance	_	50	_	Ω

AC Electrical Characteristics for 2.5V Supply

Pa	Min	Тур	Max	Unit	
Input frequency	Input frequency		-	12	MHz
Output frequency		6	-	12	MHz
Fraguency Deviation	Input Frequency = 6MHz	_	-	±0.96	%
Frequency Deviation	Input Frequency = 12MHz	_	-	±0.45	70
Output rise time (measured from 0.7V to 1.7V)		0.4	1.2	1.4	nS
Output fall time (measured	0.4	0.9	1.1	nS	
Jitter (cycle to cycle)	_	-	200	pS	
Output duty cycle	45	50	55	%	
	Input frequency Output frequency Frequency Deviation Output rise time (measured Output fall time (measured Jitter (cycle to cycle)	Output frequency Frequency Deviation Input Frequency = 6MHz Input Frequency = 12MHz Output rise time (measured from 0.7V to 1.7V) Output fall time (measured from 1.7V to 0.7V) Jitter (cycle to cycle)	Input frequency Output frequency Frequency Deviation Input Frequency = 6MHz Input Frequency = 12MHz Output rise time (measured from 0.7V to 1.7V) Output fall time (measured from 1.7V to 0.7V) Jitter (cycle to cycle) -	Input frequency	Input frequency

 $^{^*}$ XIN/CLKIN pin and $\overline{PD}~$ pin are pulled $\underline{low}~$ ** V_{DD} and XIN/CLKIN input are stable, $\overline{PD}~$ pin is made high from low.



DC Electrical Characteristics for 3.3V Supply

(Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated.)

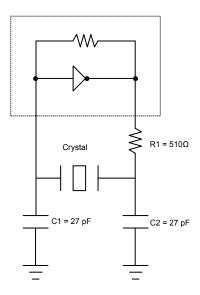
Symbol	Parameter	Min	Тур	Max	Unit
V_{IL}	Input low voltage	GND - 0.3	_	0.8	V
V_{IH}	Input high voltage	2.0	ı	V _{DD} + 0.3	V
I _{IL}	Input low current	_	ı	-35	μΑ
I _{IH}	Input high current	_	-	35	μΑ
I _{XOL}	XOUT output low current (@0.4V, V _{DD} =3.3V)	_	3	_	mA
I _{XOH}	XOUT output high current (@2.5V, V _{DD} =3.3V)	_	3	_	mA
V _{OL}	Output low voltage (V _{DD} = 3.3 V, I _{OL} = 8 mA)	_	_	0.4	V
V_{OH}	Output high voltage (V _{DD} = 3.3 V, I _{OH} = 8 mA)	2.5	-	_	V
I_{DD}	Static supply current*	_	-	10	μA
Icc	Dynamic supply current (3.3V, 8MHz and no load)	_	3.0	_	mA
V_{DD}	Operating voltage	2.7	3.3	3.6	V
t _{ON}	Power-up time(first locked cycle after power up)**	_	-	5	mS
Z _{out}	Output impedance	_	45	_	Ω
* XIN/CLKIN	pin and $\overline{\text{PD}}$ pin are pulled low				_

AC Electrical Characteristics for 3.3V Supply

Symbol	Pa	Parameter			Max	Unit
CLKIN	Input frequency		6	_	13	MHz
ModOUT	Output frequency		6	_	13	MHz
f	Frequency Deviation	Input Frequency = 6MHz	_	-	±0.96	%
f_d	Input Frequency = 13MHz	_	-	±0.43	70	
t _{LH} *	Output rise time (measure	Output rise time (measured at 0.8V to 2.0V)		1.3	1.5	nS
t _{HL} *	Output fall time (measured	Output fall time (measured at 2.0V to 0.8V)			1.2	nS
t _{JC}	Jitter (cycle to cycle)	Jitter (cycle to cycle)		-	200	pS
t_D	Output duty cycle		45	50	55	%
*t _{LH} and t _{HL} are measured into a capacitive load of 15pF						

^{**}V_{DD} and XIN/CLKIN input are stable; PD pin is made high from low.

Typical Crystal Oscillator Circuit



Typical Crystal Specifications

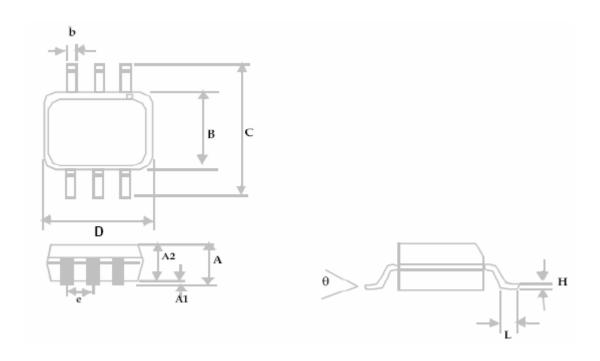
Fundamental AT cut parallel resonant crystal				
Nominal frequency	8.000 MHz			
Frequency tolerance	± 50 ppm or better at 25°C			
Operating temperature range	-25°C to +85°C			
Storage temperature	-40°C to +85°C			
Load capacitance	18pF			
Shunt capacitance	7pF maximum			
ESR	25 Ω			



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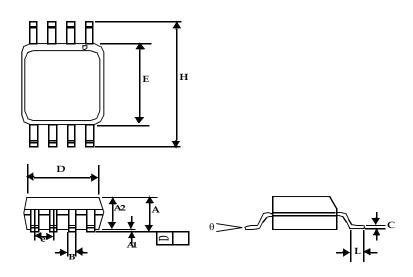
Package Information

6-pin TSOT-23 Package



	Dimensions				
Symbol	Inches		Millim	eters	
	Min	Max	Min	Max	
Α		0.04		1.00	
A1	0.00	0.004	0.00	0.10	
A2	0.033	0.036	0.84	0.90	
b	0.012	0.02	0.30	0.50	
Н	0.005	BSC	0.127 BSC		
D	0.114 BSC		2.90	BSC	
В	0.06 BSC		1.60	BSC	
е	0.0374 BSC		0.950	BSC	
С	0.11 BSC		2.80 BSC		
L	0.0118	0.02	0.30 0.50		
θ	0°	4°	0°	4°	

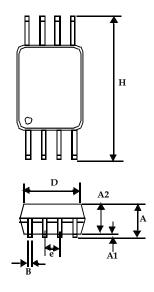
8-Pin SOIC Package

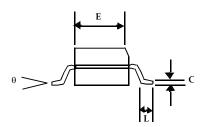


	Dimensions					
Symbol	Inches		Millim	neters		
	Min	Max	Min	Max		
A1	0.004	0.010	0.10	0.25		
Α	0.053	0.069	1.35	1.75		
A2	0.049	0.059	1.25	1.50		
В	0.012	0.020	0.31	0.51		
С	0.007	0.010	0.18	0.25		
D	0.193	BSC	4.90	4.90 BSC		
Е	0.154	BSC	3.91	BSC		
е	0.050 BSC		1.27	BSC		
Н	0.236 BSC		6.00 BSC			
L	0.016	0.050	0.41 1.27			
θ	0°	8°	0°	8°		

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TSSOP Package





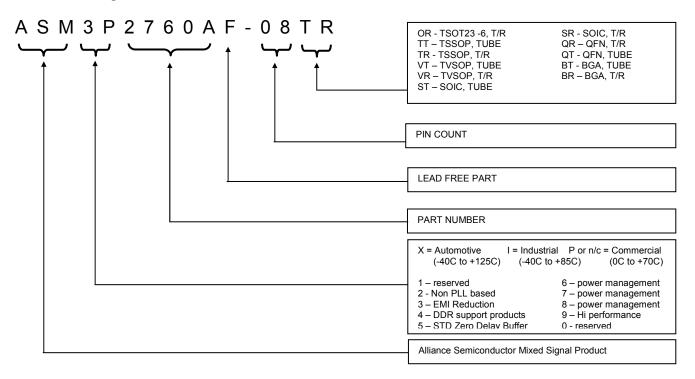
	Dimensions			
Symbol	Inches		Millimeters	
	Min	Max	Min	Max
Α		0.043		1.10
A1	0.002	0.006	0.05	0.15
A2	0.033	0.037	0.85	0.95
В	0.008	0.012	0.19	0.30
С	0.004	0.008	0.09	0.20
D	0.114	0.122	2.90	3.10
Е	0.169	0.177	4.30	4.50
е	0.026 BSC		0.65 BSC	
Н	0.252 BSC		6.40 BSC	
L	0.020	0.028	0.50	0.70
θ	0°	8°	0°	8°



Ordering Information

Part Number	Marking	Package Type	Temperature
ASM3P2760AF-06OR	E4LL	6-Pin TSOT-23, TAPE & REEL	0°C – 70°C
ASM3P2760AF-08TT	ASM3P2760AFT	8-Pin TSSOP, TUBE	0°C – 70°C
ASM3P2760AF-08TR	ASM3P2760AFT	8-Pin TSSOP, TAPE & REEL	0°C – 70°C
ASM3P2760AF-08ST	ASM3P2760AFS	8-Pin SOIC, TUBE	0°C – 70°C
ASM3P2760AF-08SR	ASM3P2760AFS	8-Pin SOIC, TAPE & REEL	0°C – 70°C
ASM3P2760A-06OR	E1LL	6-Pin TSOT-23, TAPE & REEL	0°C – 70°C
ASM3P2760A-08TT	ASM3P2760AT	8-Pin TSSOP, TUBE	0°C – 70°C
ASM3P2760A-08TR	ASM3P2760AT	8-Pin TSSOP, TAPE & REEL	0°C – 70°C
ASM3P2760A-08ST	ASM3P2760AS	8-Pin SOIC, TUBE	0°C – 70°C
ASM3P2760A-08SR	ASM3P2760AS	8-Pin SOIC, TAPE & REEL	0°C – 70°C

Device Ordering Information



Licensed under U.S Patent Nos 5,488,627 and 5,631,921





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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

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